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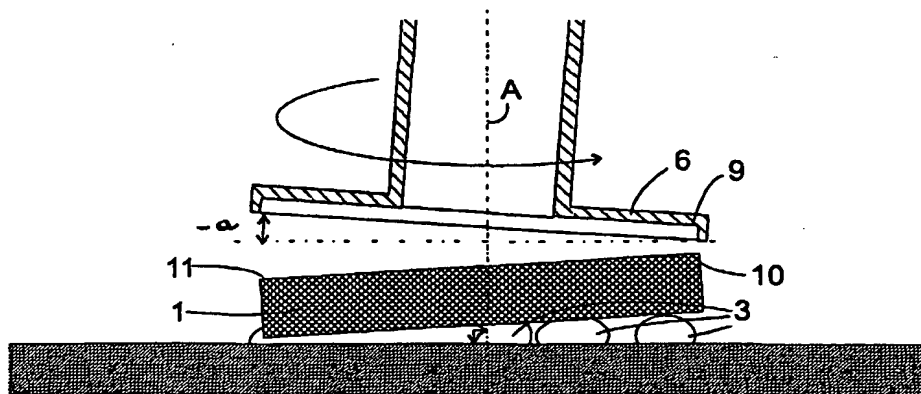
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(54) Title: METHOD FOR GLUING A CIRCUIT COMPONENT TO A CIRCUIT SUBSTRATE



(57) Abstract: A circuit component (1) is glued to the circuit substrate (2) by the following steps: a) seizing a circuit component (1) using a gripper (4); b) moving the gripper (4) towards the surface of the circuit substrate (2) up to a target distance from the surface at which adhesive (3) applied between the circuit component (1) and the circuit substrate (2) is pressed; C) releasing the circuit component (1) and removing the gripper (4) from the circuit component (1); d) turning the gripper (4) around an axis (A) perpendicular to the surface of the circuit substrate (2); e) moving the gripper (4) into the target distance again; and f) removing the gripper (4) again.



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